

Harmonized system of quality assessment for electronic components: Basic specification: Scanning electron microscope inspection of semiconductor dice

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- Association of Control Manufacturers TACMA (BEAMA)
- Association of Franchised Distributors of Electronic Components
- British Industrial Measuring and Control Apparatus Manufacturers' Association
- British Standards Society
- Control and Automation Manufacturers' Association (BEAMA)
- Department of Industry Computers Systems and Electronics
- Department of Trade
- Electronic Components Industry Federation
- Electronic Engineering Association
- Engineering Equipment Users' Association
- Ministry of Defence
- National Supervising Inspectorate
- Post Office
- Scientific Instrument Manufacturers' Association
- Society of British Aerospace Companies Limited
- Telecommunication Engineering and Manufacturing Association (TEMA)

This British Standard, having been prepared under the direction of the Electronic Components Standards Committee, was published under the authority of the Board of BSI and comes into effect on 30 August 1985

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Contents

	Page
Committee responsible	Inside front cover
National foreword	iii
Foreword	ii
1 Scope	1
1.1 General	1
1.2 Alternative standards	1
2 Definitions	1
2.1 SEM inspection Lot	1
2.2 Oxide steps	1
2.3 Multi-level metallisation system	1
2.4 Multi-layered-metal	1
2.5 Critical areas	1
2.6 Failed dice	1
3 Requirements	2
3.1 Equipment	2
3.1.1 Scanning electron microscope	2
3.1.2 Deposition of a conductive film	2
3.2 Sample selection	2
3.2.1 Wafer sample selection from a metallisation run	2
3.2.2 Wafer sample selection from a procured lot	2
3.2.3 Die sample selection	2
3.2.3.1 Non-glassivated devices	2
3.2.3.2 Glassivated devices	2
3.2.3.3 Multi-level systems	3
3.3 Die sample preparation	3
3.3.1 Deposition of a conductive film	3
3.3.2 Mounting on specimen holder	3
3.4 Die sample examination, general requirements	3
3.4.1 General	3
3.4.2 Viewing angle	3
3.4.3 Viewing direction	3
3.4.4 Magnification	4
3.5 Die sample examination, detail requirements	4
3.5.1 Discrete semiconductor devices	4
3.5.1.1 Oxide steps	4
3.5.1.2 General metallisation	4
3.5.2 Integrated circuits	4
3.5.2.1 Oxide steps	4
3.5.2.2 General metallisation	4
3.5.3 Multi-layered-metal interconnection systems	4
3.6 Specimen after examination	4
3.7 Acceptance requirements	4
3.7.1 General	4
3.7.2 Single wafer acceptance basis	4
3.7.3 Lot acceptance basis	5
3.8 Accept/Reject criteria	5

	Page
4 Documentation	5
4.1 Photographic	5
4.2 Information	5
4.3 Distribution of documentation	5
Chart 1 — Sample selection from non-glassivated devices	10
Chart 2 — Sample selection from glassivated devices	11
Chart 3 — Sample selection from glassivated devices	12
Chart 4 — Sample selection from glassivated devices	13
Chart 5 — Sample selection from glassivated devices (procured wafers)	14
Chart 6 — Sample selection for multi-level systems	15
Figure 1 — Viewing angle	7
Figure 2 — Wafer sample selection	8
Figure 3 — Dice selection on wafer diameter	8
Figure 4 — Dice selection on wafer segment	9
Table 1 — Examination procedure for sample dice	6

National foreword

This British Standard has been prepared under the direction of the Electronic Components Standards Committee. It is identical with CENELEC Electronic Components Committee (CECC) 00013:1984 “*Harmonized system of quality assessment for electronic components: Basic specification: Scanning electron microscope inspection of semiconductor dice*”.

This standard is a harmonized specification within the CECC system.

Terminology and conventions. The text of the CECC specification has been approved as suitable for publication as a British Standard without deviation. Some terminology and certain conventions are not identical with those used in British Standards; attention is drawn especially to the following.

The comma has been used as a decimal marker. In British Standards it is current practice to use a full point on the baseline as the decimal marker.

NOTE The last part (beginning “and copies”) of paragraph 4 of the foreword is not applicable for this British Standard

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

Summary of pages

This document comprises a front cover, an inside front cover, pages i to iv, the CECC title page, page ii, pages 1 to 15 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

English version

Harmonized System of Quality Assessment for
Electronic Components

BASIC SPECIFICATION:
**SCANNING ELECTRON
MICROSCOPE INSPECTION
OF SEMICONDUCTOR DICE**

Système Harmonisé d'Assurance de la Qualité
des Composants Electroniques

SPECIFICATION DE BASE:
**CONTROLE AU MICROSCOPE
ELECTRONIQUE A BALAYAGE
DES PASTILLES
A SEMICONDUCTEURS**

Harmonisiertes Gütebestätigungssystem für
Bauelemente der Elektronik

GRUNDSPEZIFIKATION:
**PRÜFUNG
VON HALBLEITERCHIPS
MIT RASTER-
ELEKTRONENMIKROSKOP**



1

Issue
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Ausgabe

CECC 00013

1984

Foreword

The CENELEC Electronic Components Committee (CECC) is composed of those member countries of the European Committee for Electrotechnical Standardization (CENELEC) who wish to take part in a harmonized System for electronic components of assessed quality.

The object of the System is to facilitate international trade by the harmonization of the specifications and quality assessment procedures for electronic components, and by the grant of an internationally recognized Mark, or Certificate, of Conformity. The components produced under the System are thereby accepted by all member countries without further testing.

This specification has been formally approved by the CECC, and has been prepared for those countries taking part in the System who wish to issue national harmonized specifications for SCANNING ELECTRON MICROSCOPE INSPECTION OF SEMICONDUCTOR DICE. It should be read in conjunction with the current regulations for the CECC System.

Preface

This basic specification was prepared by the ESA/SCCG. It was sponsored administratively by CECC WG 5 who made not contribution to the technical contents.

The text of this specification was circulated to the CECC for voting in the document indicated below and was approved by the President of the CECC for publication as a CECC Specification.

Document	Date of Voting	Report on the Voting
CECC(Secretariat) 1384	November 1983	CECC(Secretariat) 1449A